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(54) **METHOD FOR MANUFACTURING WIRING SUBSTRATE**

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ABSTRACT

A method for manufacturing a wiring substrate includes forming conductor pads on a surface of an insulating layer, positioning, on or in the insulating layer, an electronic component having electrode pads, forming a second insulating layer covering the surface of the insulating layer, conductor pads and electronic component, forming first via holes exposing the conductor pads, applying a first desmear treatment to the second insulating layer such that residues are removed from the first via holes, forming second via holes in the second insulating layer after the first desmear treatment such that the second via holes expose the electrode pads of the electronic component positioned on or in the insulating layer, applying a second desmear treatment to the second insulating layer such that residues are removed from the second via holes, forming first via conductors in the first via holes, and forming second via conductors in the second via holes.

